GSM3106ZF

30V N-Channel MOSFET

Product Description

The device uses trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

It is well suited for high efficiency fast switching applications.

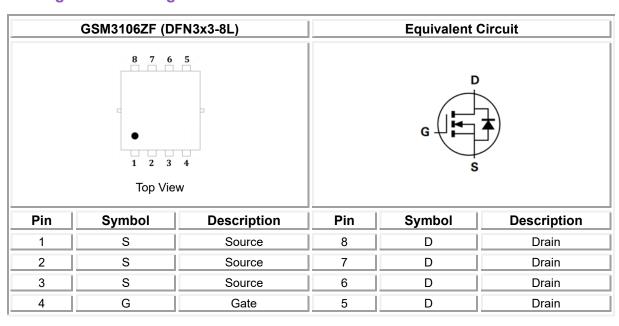
Features

- 30V, $R_{DS(ON)}$ 6m Ω max @ V_{GS} =10V
- DFN3x3-8L Package
- RoHS Compliant and Halogen Free

Applications

- Power Management in NB
- POL Applications
- DC-DC Switching Applications

Packages & Pin Assignments





Ordering and Marking Information

	Ordering Info	ormation	
Part Number Package Part Marking Quantity /			
GSM3106ZF	DFN3x3-8L	3106AZF	5,000 PCS
GSM3106 [] [2			
- Product Code: GSM3106	- Package Code:		
	Marking Info	rmation	
	- Product Code: 3106AZF		
3106AZF	- GS Code:		



Absolute Maximum Ratings (T_J=25°C unless otherwise noted)

Symbol	Parameter		Value	Unit
V _{DS}	Drain-Source Voltage		30	V
V _G s	Gate-Source Voltage		±20	V
I _D	Continuous Drain Current	T _C =25°C	54	А
		T _C =70°C	43	
I _{DM}	Pulsed Drain Current ¹		80	Α
E _{AS}	Single Pulse Avalanche Energy ^{1, 2}		40	mJ
	Power Dissipation T _C =25°C		26.6	W
P _D	P _D Power Dissipation T _C =70°C		17.1	W
R _{θJC}	Thermal Resistance-Junction to Case		4.7	°C/W
TJ	Operating Junction Temperature Range		-55 to +150	$^{\circ}\!\mathbb{C}$
T _{STG}	Storage Temperature Range		-55 to +150	$^{\circ}\mathbb{C}$

NOTE:

- Pulsed width is limited by the maximum junction temperature. V_{DD} =15V, V_{GS} =10V, L=0.1mH, I_{AS} =20A. Surface Mounted on 1in² pad area.

$\textbf{Electrical Characteristics} \,\, (T_A \!\!=\!\! 25^{\circ}\mathrm{C} \,\, \text{Unless otherwise noted})$

Symbol	Parameter	Conditions	Min	Тур	Max	Unit	
	Static	Characteristics					
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	30			V	
I _{DSS}	Drain-Source Leakage Current	V _{DS} =30V, V _{GS} =0V			1	uA	
Igss	Gate Leakage Current	V _{DS} =0V, V _{GS} =±20V			±100	nA	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	1.0		2.5	V	
R _{DS(on)}	D : 0	V _{GS} =10V, I _D =20A		4.8	6		
	Drain-Source On-Resistance 4	V _{GS} =4.5V, I _D =10A		6.9	9	mΩ	
V _{SD}	Diode Forward Voltage ⁴	V _{GS} =0V, I _S =2A			1	V	
	Gate Cha	arge Characteristics					
Qg	Total Gate Charge			22.3			
Qgs	Gate-Source Charge V _{DD} =15V, I _D =12A V _{GS} =10V			2.2		nC	
Q_{gd}	Gate-Drain Charge	VGS=10V		3.5		<u> </u>	
	Dynam	ic Characteristics					
Ciss	Input Capacitance			1155			
Coss	Output Capacitance	\/po=15\/\/oo=0\/		456		pF	
Crss	Reverse Transfer Capacitance	1-1.0IVII 12		72			
t _{d(on)}	Turn-On Time			3.5			
tr	Rise Time	V _{DD} =15V, V _{GS} =10V,		5.5			
$t_{d(off)}$	Turn-Off Time	Rg=3Ω, I _D =9A		13.5		ns	
t _f	Fall Time			4.6			

NOTE:

4. Pulse width \leq 300us , duty cycle \leq 2%.



Typical Performance Characteristics

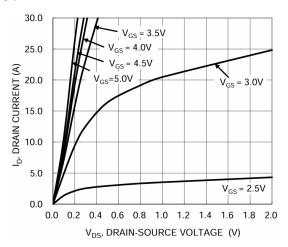


Fig 1. Output Characteristics

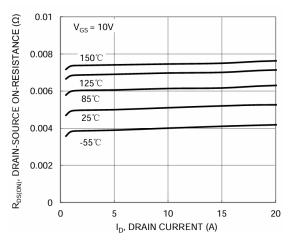


Fig 3. R_{DSON} vs. I_D

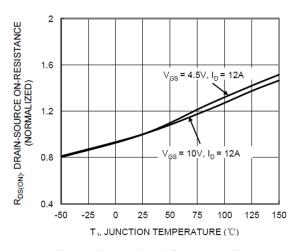


Fig 5. Normalized R_{DSON} vs. T_J

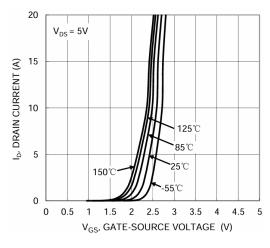


Fig 2. Transfer Characteristics

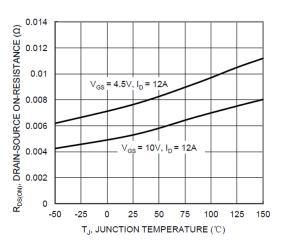


Fig 4. R_{DSON} vs. T_J

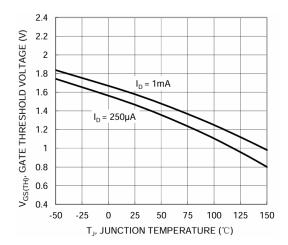


Fig 6. V_{th} vs. T_J

Typical Performance Characteristics (Continued)

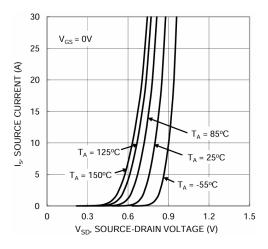


Fig 7. V_{SD} vs. I_D

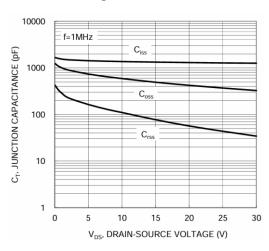


Fig 9. Capacitance Characteristics

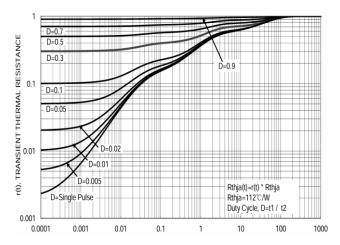


Fig 11. Normalized Transient Thermal Resistance

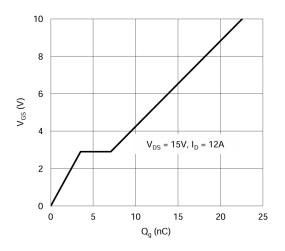


Fig 8. Gate Charge Characteristics

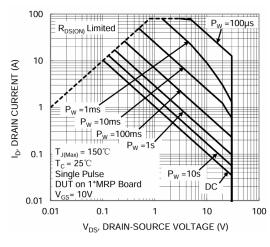
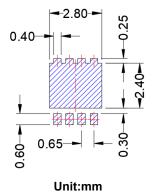


Fig 10. Safe Operating Area



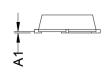
DFN3X3-8L

Package Dimension



Recommended Land Pattern





	Dimensions				
0	Millimeters		Inches		
Symbol	Min	Max	Min	Max	
Α	0.70	0.90	0.028	0.035	
A 1	0.00	0.05	0.000	0.002	
b	0.24	0.37	0.009	0.015	
С	0.10	0.25	0.004	0.010	
D	2.90	3.25	0.114	0.128	
D1	2.35	2.60	0.093	0.102	
E	3.05	3.45	0.120	0.136	
E1	2.90	3.20	0.114	0.126	
E2	1.35	2.00	0.053	0.079	
E3	0.30	0.60	0.012	0.024	
е	0.65 BSC		0.026 BSC		
L	0.02	0.2	0.001	0.008	
L1	0.28	0.5	0.011	0.020	
L2		0.15		0.006	

NOTE

Dimensions are exclusive of Burrs, Mold Flash & Tie Bar extrusions.



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